

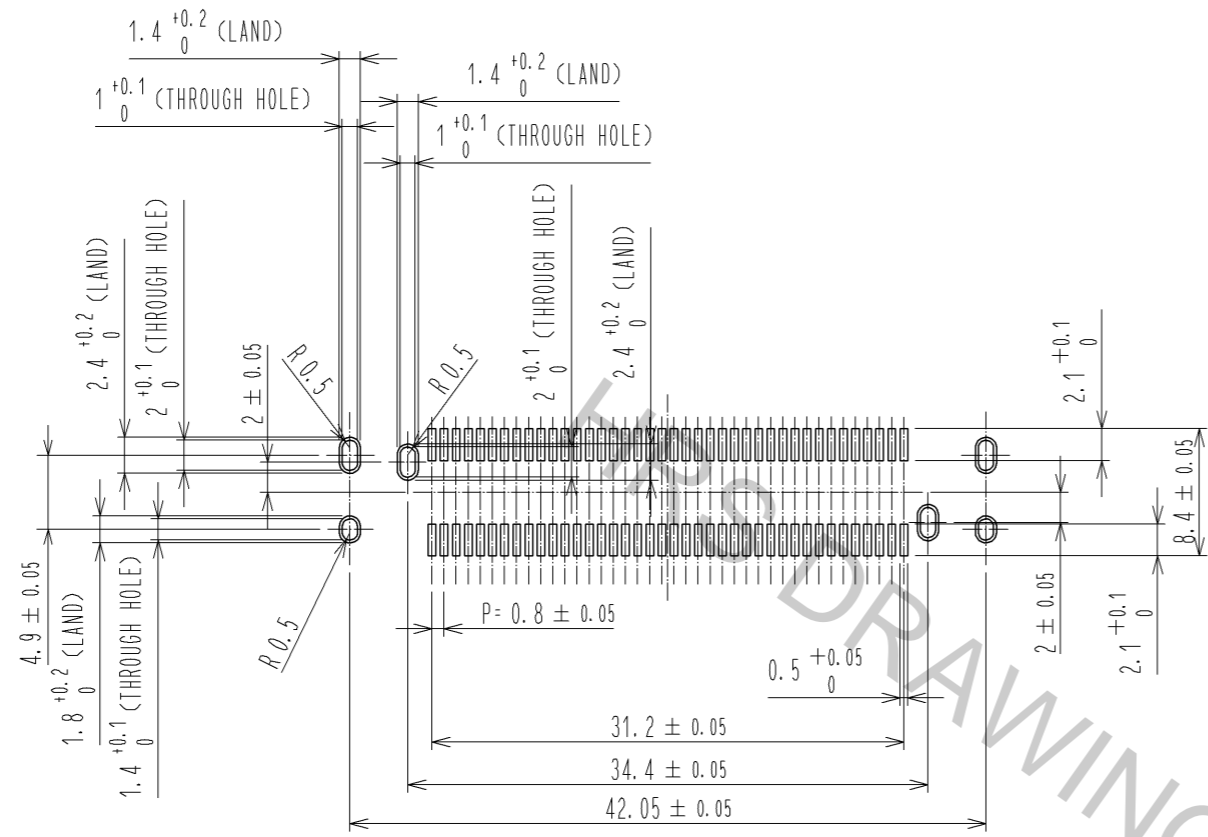
- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A->SIGNAL CONTACT->MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
 - ③ MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
 - ④ IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2) REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
 - ⑤ THIS IS PACKAGED IN TRAY. (50pcs/TRAY)
 - ⑥ BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
 - ⑦ THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

7	POLYIMIDE	
6	POLYSTYRENE	
5	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm
		LEAD AREA:TIN-PLATING 1 μm
		UNDER PLATING:NICKEL 1.3 μm
4	COPPER ALLOY	CONTACT AREA:GOLD 0.1 μm
		LEAD AREA:TIN-PLATING 1 μm
		UNDER PLATING:NICKEL 1.3 μm
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm LEAD AREA:GOLD 0.03 μm UNDER PLATING:NICKEL 1.3 μm
2	POLYAMIDE	BLACK UL94V-0
1	POLYAMIDE	BLACK UL94V-0

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
7	POLYIMIDE						
6	POLYSTYRENE						
5	COPPER ALLOY						
4	COPPER ALLOY						
3	PHOSPHOR BRONZE						
2	POLYAMIDE						
1	POLYAMIDE						

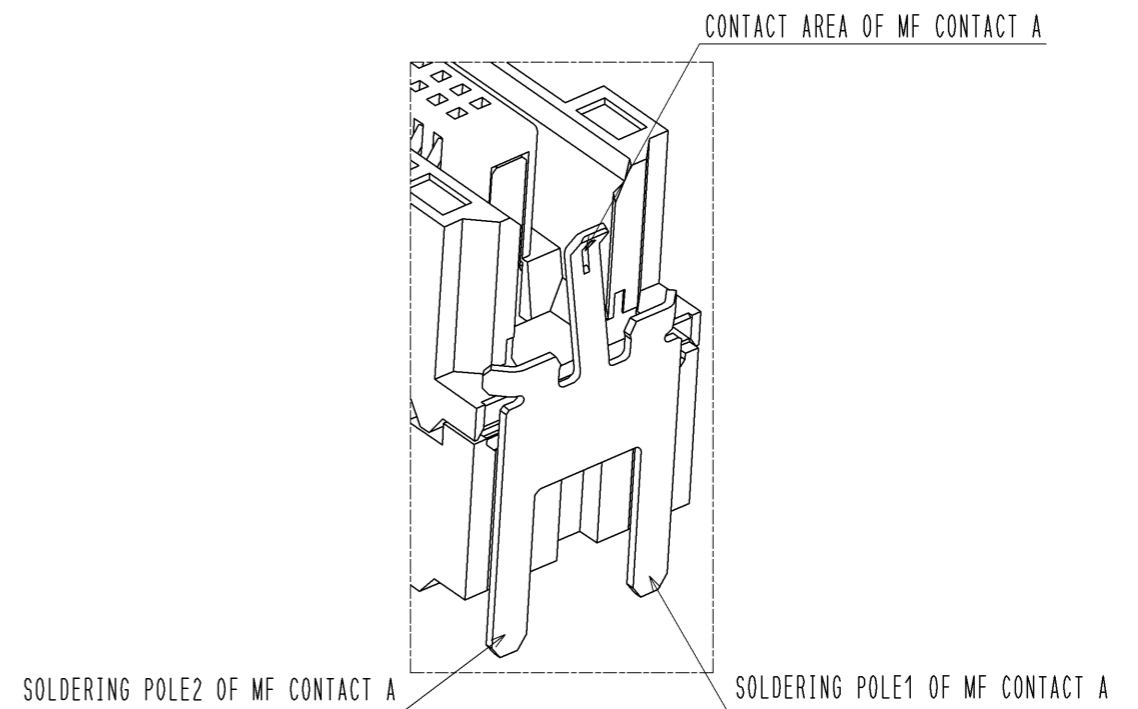
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	△				
APPROVED : HS. OKAWA			11.08.24	DRAWING NO. EDC3-334388-00		
CHECKED : KI. HIROKAWA			11.08.24	PART NO. FX18-80S-0.8SV15		
DESIGNED : TH. SANO			11.08.24	CODE NO. CL579-0028-9-00		
DRAWN : TH. SANO			11.08.24	1/2		

RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
 (PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)

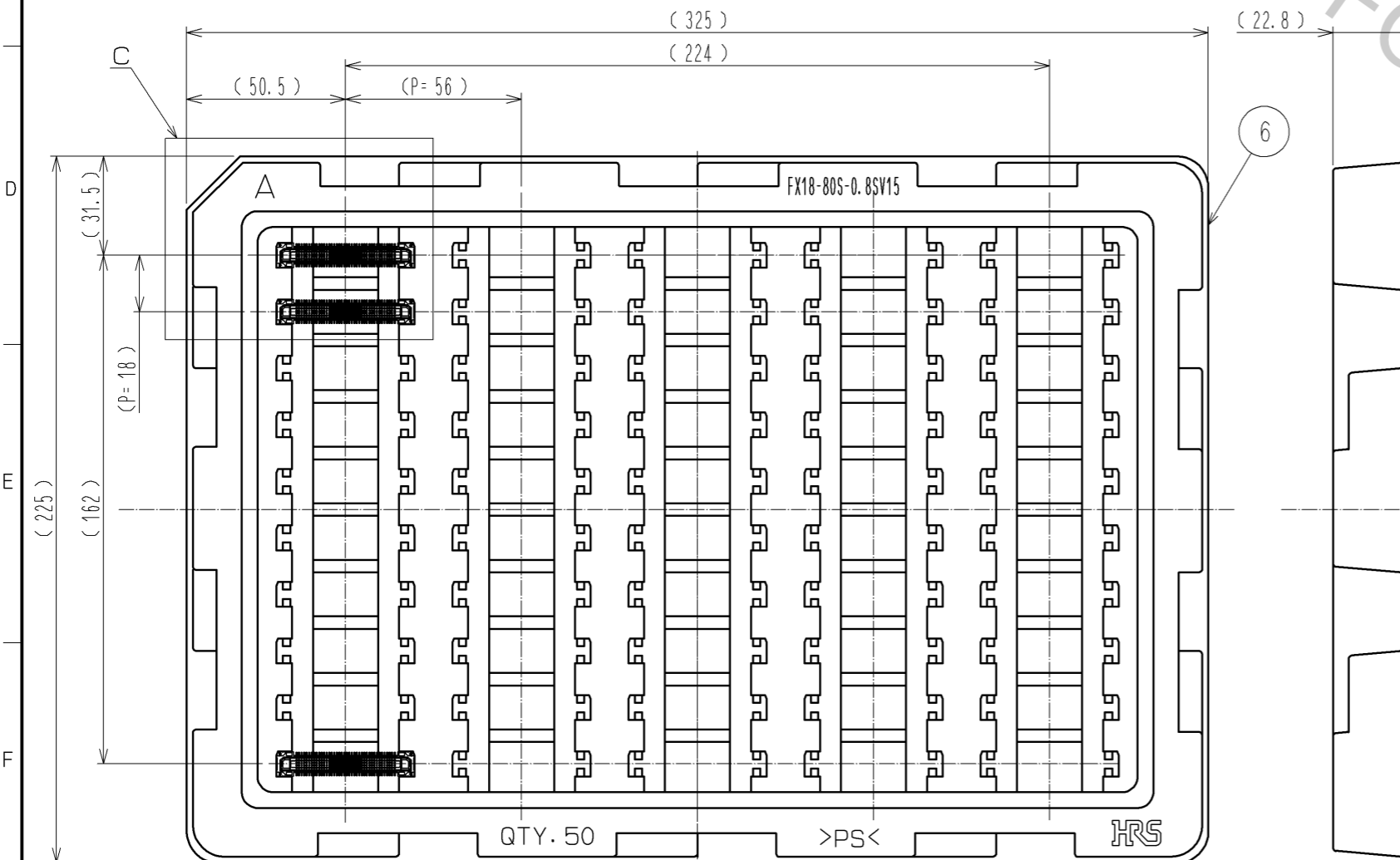


5 DRAWING FOR PACKING(1:2)

8 CONFIGURATION OF MF CONTACT A

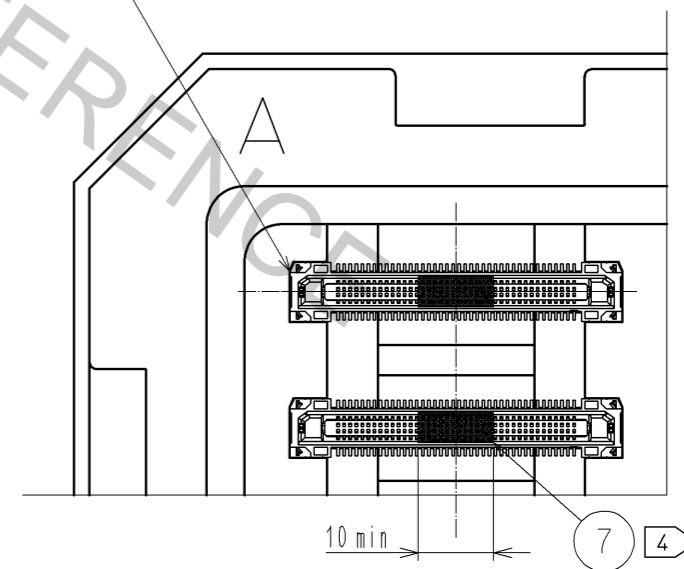


NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
 BE SURE TO CONNECT TO THE SAME CIRCUIT.



FX18-80S-0.8SV15

C(1:1)



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		△ 2/2